



Material Content Data Sheet



Sales Product Name		IPD70R950CE		Issued		19. January 2018		
MA#		MA001469478						
Package		PG-TO252-3-344		Weight*		322.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.509	0.78	0.78	7776	7776
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		447	
	non noble metal	copper	7440-50-8	143.904	44.60	44.65	445985	446566
	non noble metal	aluminium	7429-90-5	0.431	0.13	0.13	1335	1335
wire	non noble metal	aluminium	7429-90-5	0.431	0.13	0.13	1335	1335
encapsulation	organic material	carbon black	1333-86-4	0.681	0.21		2111	
	plastics	epoxy resin	-	18.393	5.70		57003	
	inorganic material	silicondioxide	60676-86-0	117.169	36.31	42.22	363130	422244
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11881	11881
solder	non noble metal	tin	7440-31-5	0.050	0.02		156	
	noble metal	silver	7440-22-4	0.063	0.02		195	
	non noble metal	lead	7439-92-1	2.406	0.75	0.79	7457	7808
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		102	
	non noble metal	copper	7440-50-8	32.995	10.23	10.24	102257	102390
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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